



## Material Content Data Sheet



Sales Product Name	SAK-C167CR-LM HA+			Issued		20. July 2018		
MA#	MA001395386							
Package	PG-MQFP-144-11			Weight*		4194.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	25.986	0.62	0.62	6195	6195
leadframe	non noble metal	magnesium	7439-95-4	0.976	0.02		233	
	inorganic material	silicon	7440-21-3	4.227	0.10		1008	
	non noble metal	nickel	7440-02-0	19.510	0.47		4651	
	non noble metal	copper	7440-50-8	625.625	14.92	15.51	149152	155044
wire	noble metal	gold	7440-57-5	3.226	0.08	0.08	769	769
encapsulation	organic material	carbon black	1333-86-4	10.440	0.25		2489	
	plastics	epoxy resin	-	441.946	10.54		105362	
	inorganic material	silicondioxide	60676-86-0	3027.503	72.17	82.96	721770	829621
leadfinish	non noble metal	tin	7440-31-5	19.304	0.46	0.46	4602	4602
plating	noble metal	silver	7440-22-4	10.582	0.25	0.25	2523	2523
glue	plastics	acrylic resin	-	1.045	0.02		249	
	noble metal	silver	7440-22-4	4.180	0.10	0.12	997	1246
*deviation	< 10%	Sum in total:			100.00			1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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